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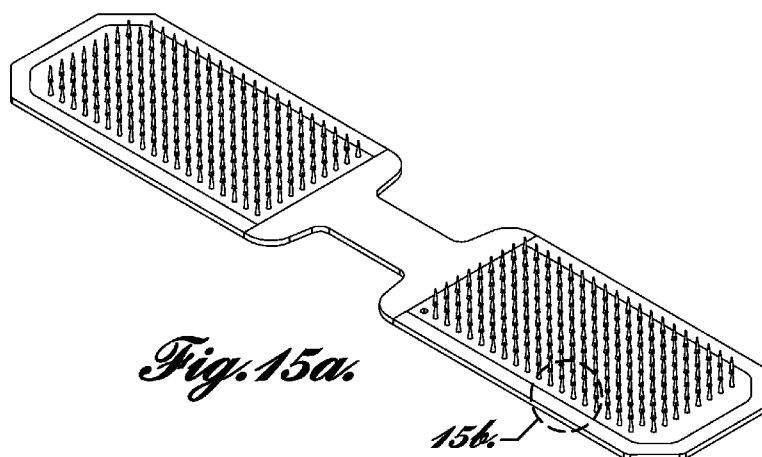
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(54) Title: MICROSTRUCTURE-BASED WOUND CLOSURE DEVICES



(57) Abstract: The present invention relates generally to wound closure devices comprising one or more microstructures. The devices are designed such that the microstructures are able to grip the skin or tissue surrounding a wound, optionally closing the wound, or securing the tissue or skin in place. Also provided are wound closure systems that comprise one or more microstructure wound closure devices along with other components, such as protective covers and wound healing therapeutics. A variety of packaging specifications are disclosed, as is a dispenser apparatus configured to enable simple one-handed application of the wound closure devices. Methods described herein provide for the closure of various wounds with the wound closure devices and systems.

